

Software of the Silicon Trackers in CEPCSW

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Silicon Tracker TDR meeting

Mar. 07, 2025

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Introduction

Physics process	Measurands	Requirement on tracker
$ZH, Z \rightarrow e^+e^-(\mu^+\mu^-), H \rightarrow \mu^+\mu^-$	$m_H, \sigma(ZH), \text{BR}(H \rightarrow \mu^+\mu^-)$	$\Delta(1/p_T) = 2 \times 10^{-5} \oplus \frac{0.001}{p(\text{GeV}) \sin^{3/2}\theta}$

- The silicon trackers @CEPC will play an important role in detecting high momentum charged particle, be helpful for low momentum region, and unique for those tracks that can not reach TPC.

- Vertex
- ITK
- OTK

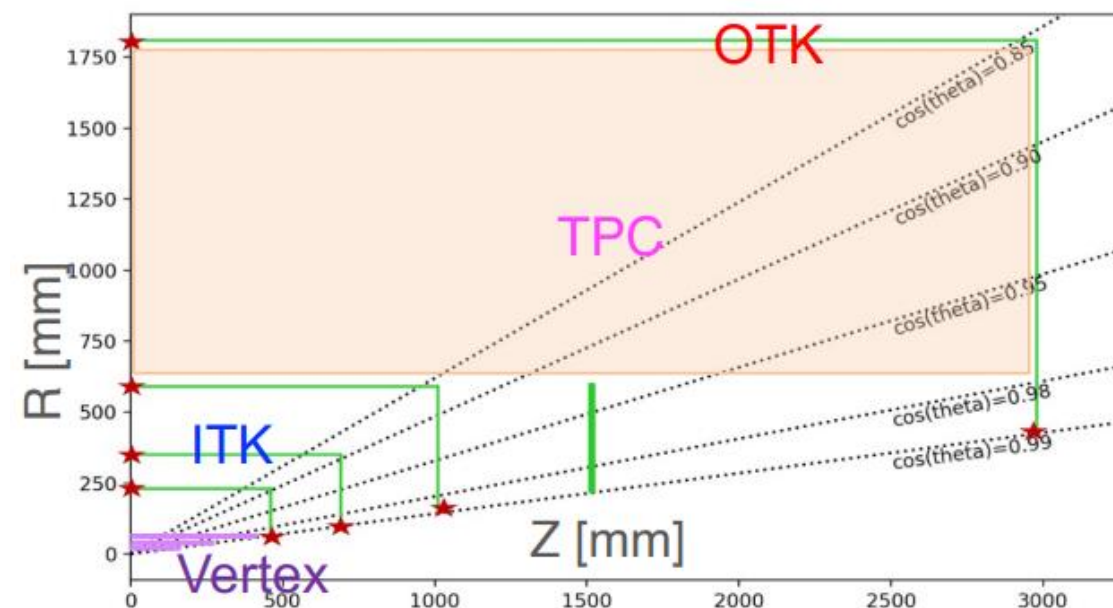
- Challenge on application of new technology

- Stitching vertex
- LGAD

- On software, requirement on high tracking efficiency and accurate performance of reconstruction

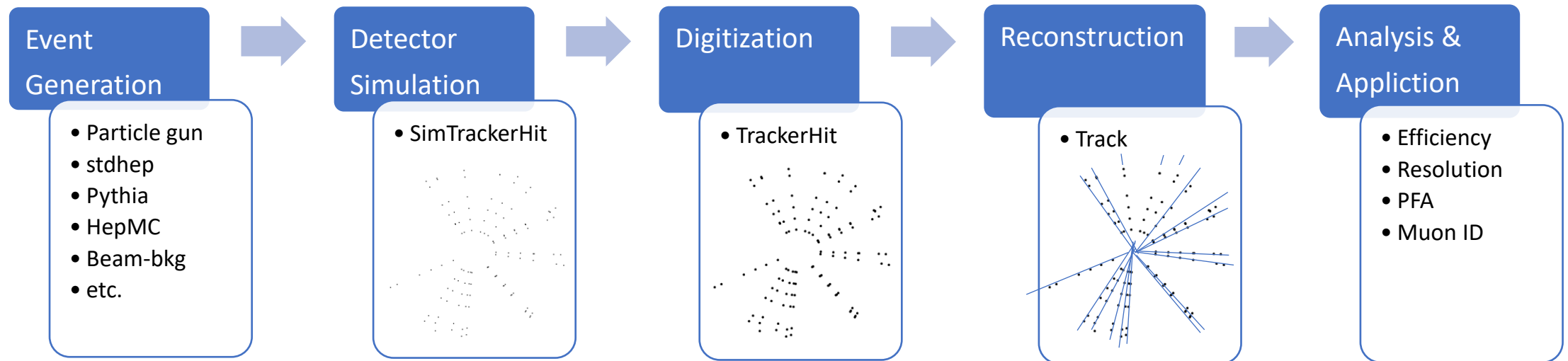
- Application at the TDR stage

- Simulation to estimation background
- Track performance for tracker optimization
- Track objects for PFA, physical analysis

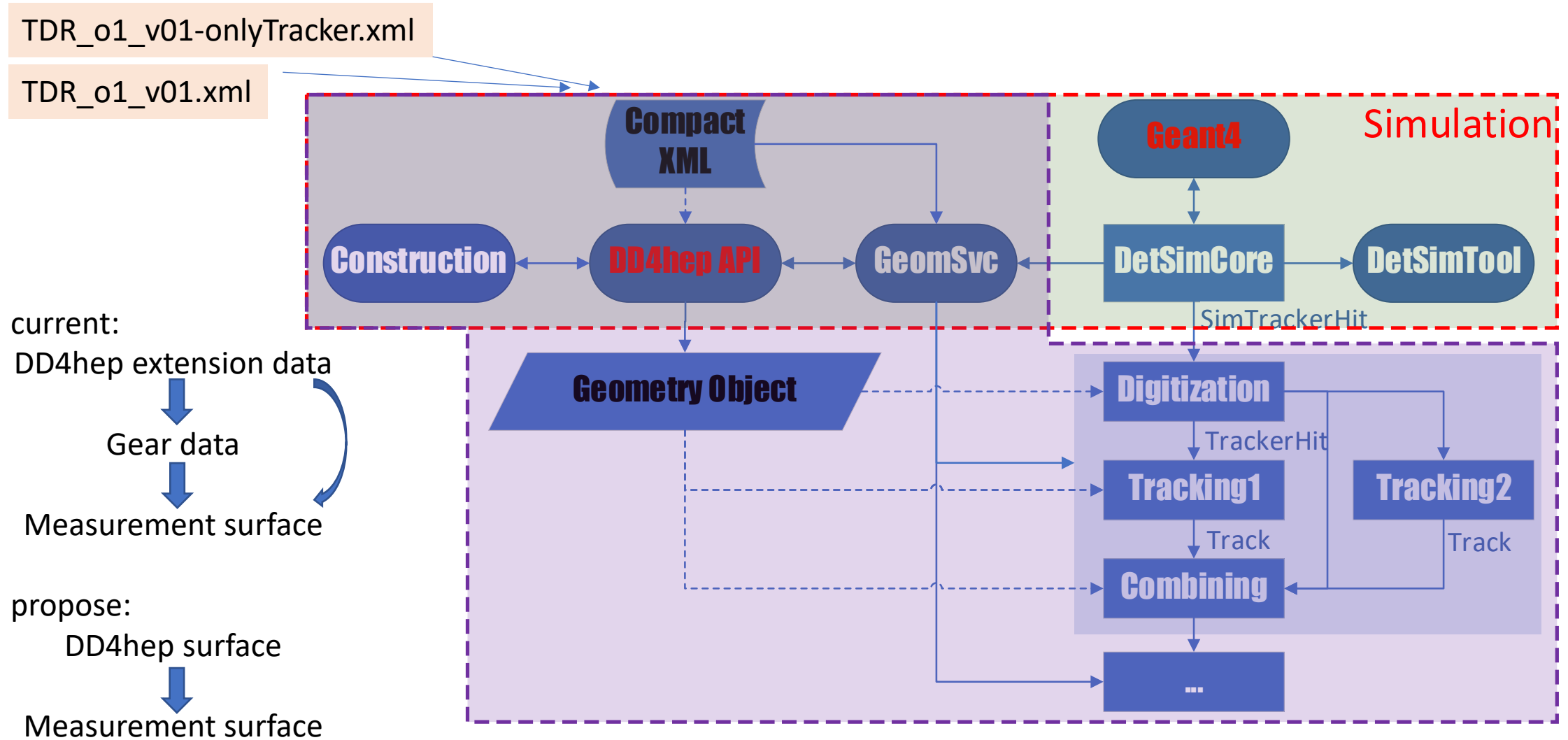


Simulation and Reconstruction Chain

- Full simulation is performed in CEPCSW, and some fast simulation tools for trackers such as LDT, Delphes, tkLayout etc. are applied in standalone.
- The standard chain of MC simulation:



Implementation and Transmit of Geometry



Sensitive Detector

■ SD in G4 simulation: G4Step → G4TrackerHit → SimTrackerHit

● step length through option

✓ <detector name="VXD" ... limits="tracker_limits" ...>

✓ if not set, use Geant4 default

● combine steps to one hit

✓ <detector name="VXD" ... combineHits="true" ...>

✓ if not set, default is false

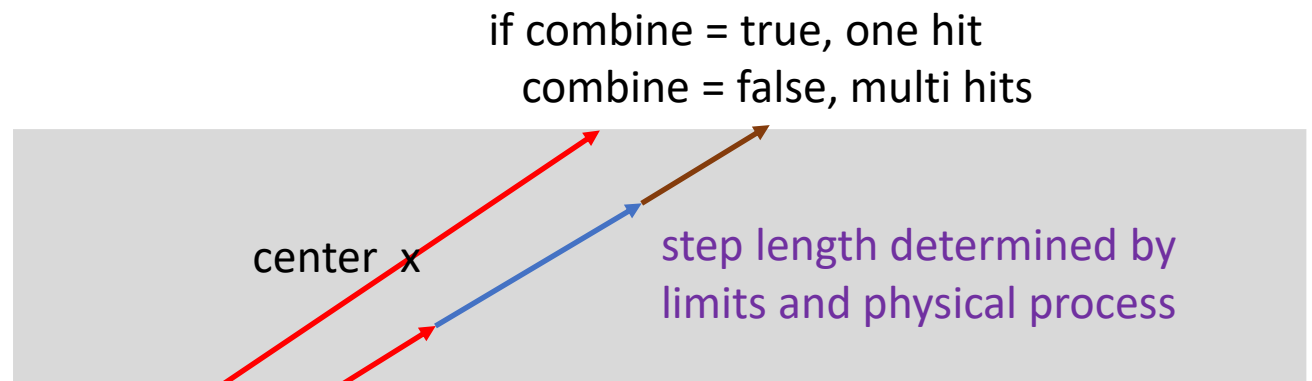
```
<limitset name="tracker_limits">
  <limit name="step_length_max" particles="*" value="5.0" unit="mm" />
</limitset>
<limitset name="detail_limits">
  <limit name="step_length_max" particles="*" value="0.005" unit="mm" />
</limitset>
```

■ Save the center position of start and end as the position of SimTrackerHit

■ Save the direction from start to end as the direction of momentum of SimTrackerHit

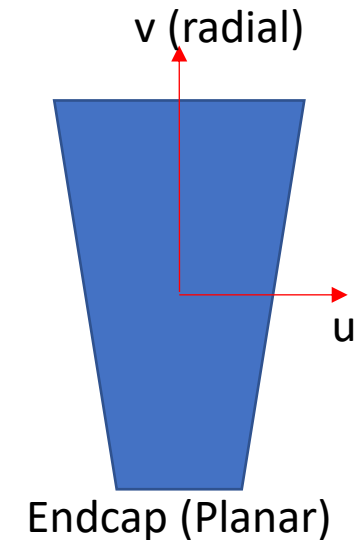
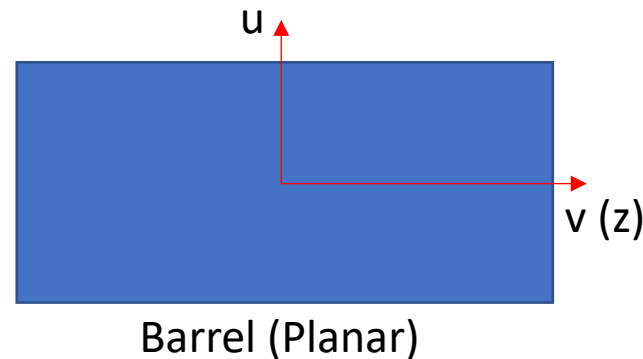
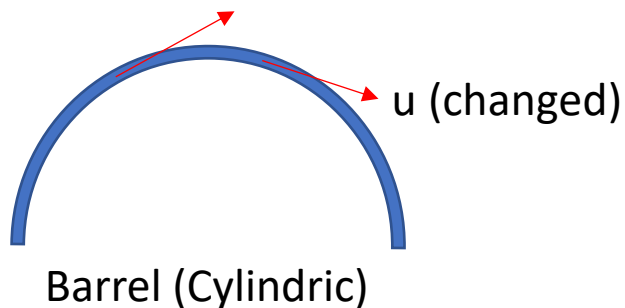
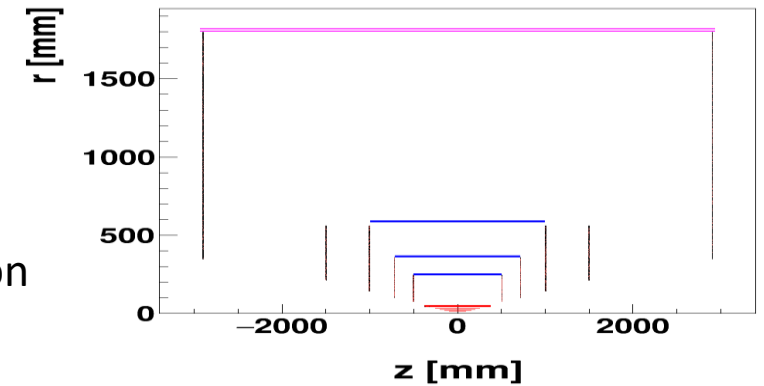
edm4hep::SimTrackerHit
cell ID
deposited energy
time
path length
position
momentum
MCParticle
quality

Volume of sensor



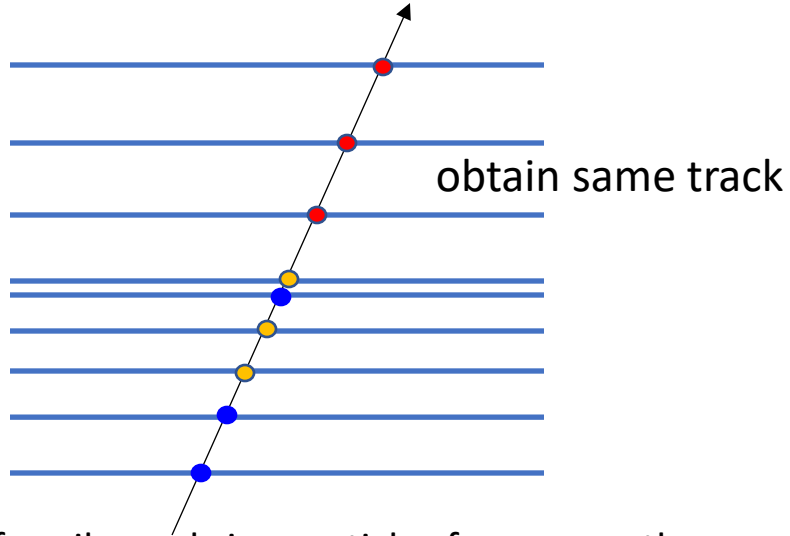
Digitization

- Gaussian smearing on SimTrackerHit at measurement dimension (u,v)
 - pixel: 2D (u,v)
 - strip: 1D $(u,0)$ or $(0,v)$
- Fixed spatial resolution or Parameterized spatial resolution through option
 - VXD: $5\mu\text{m}$, ITK: $8\mu\text{m}$ ($40\mu\text{m}$), OTK: $10\mu\text{m}$ (1mm), TPC: varied with drift length
- Measurement surface at the center plane, consistent with the general simulated hit
- Drop threshold
 - Hit efficiency between $[0,1]$: current global for each sub-detector, **local option for each sensor, support to make dead for whole sensor**
 - Deposited energy in step



Track Finding

■ seed find



■ prepare for pile up: bring particles from more than one bunch to vertex

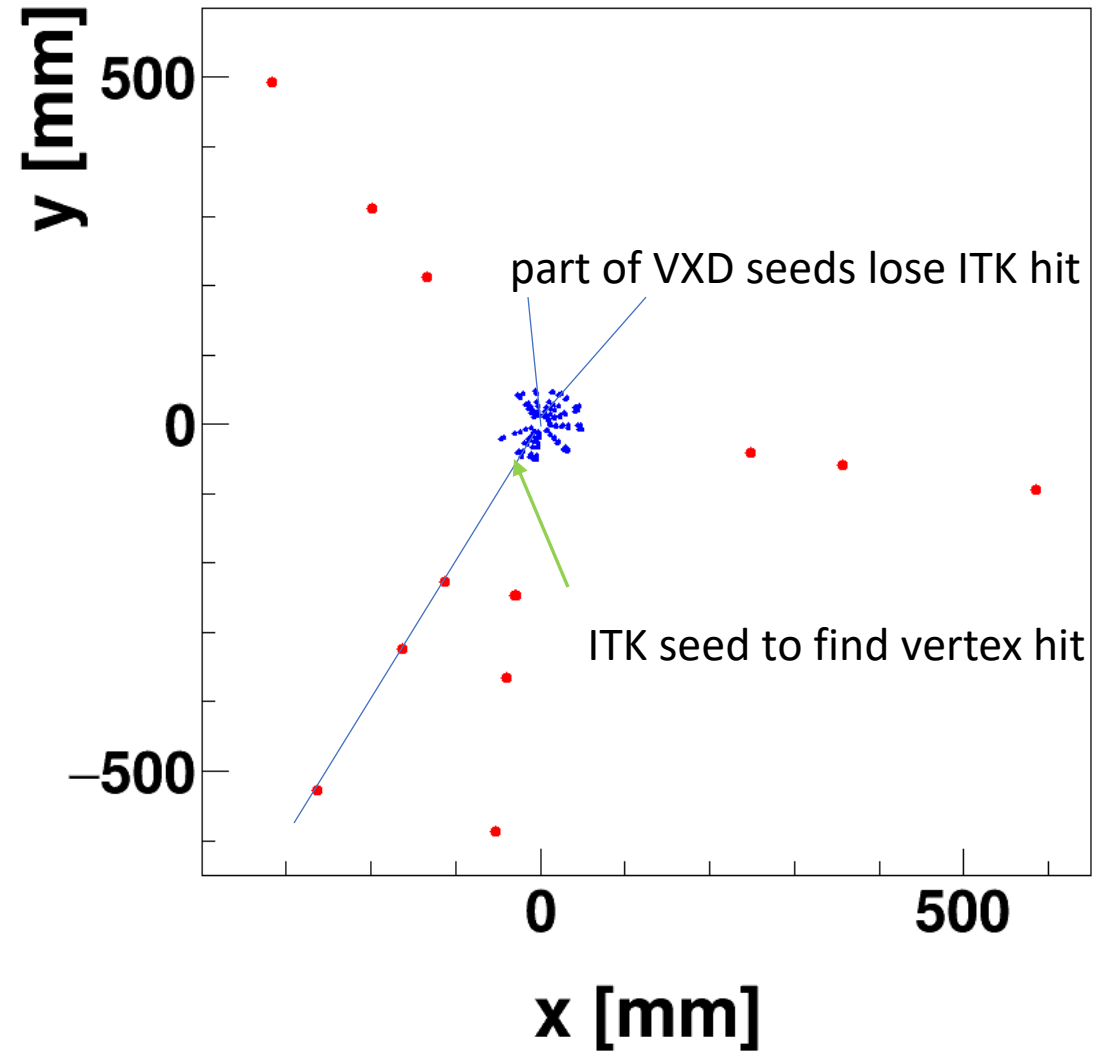
● VXD seeds

● ITK seeds

■ The track candidates without ITK hit

● high momentum: drop

● low momentum can not reach ITK: d_0 , z_0 to remove beam background $p_T \sim 120 \text{ MeV}$



Tracking Options

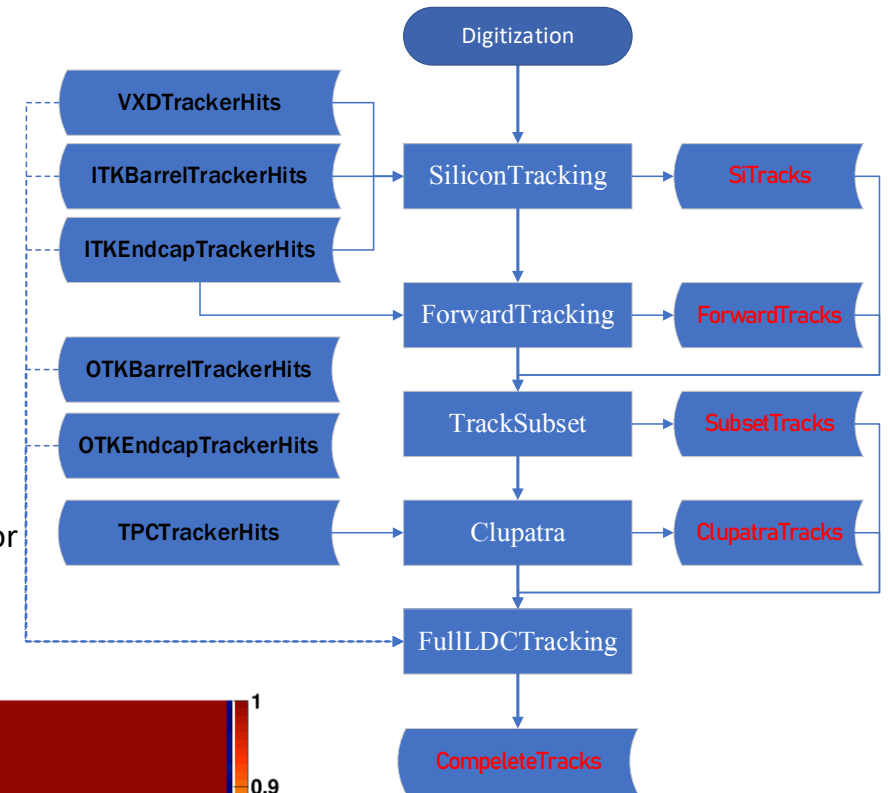
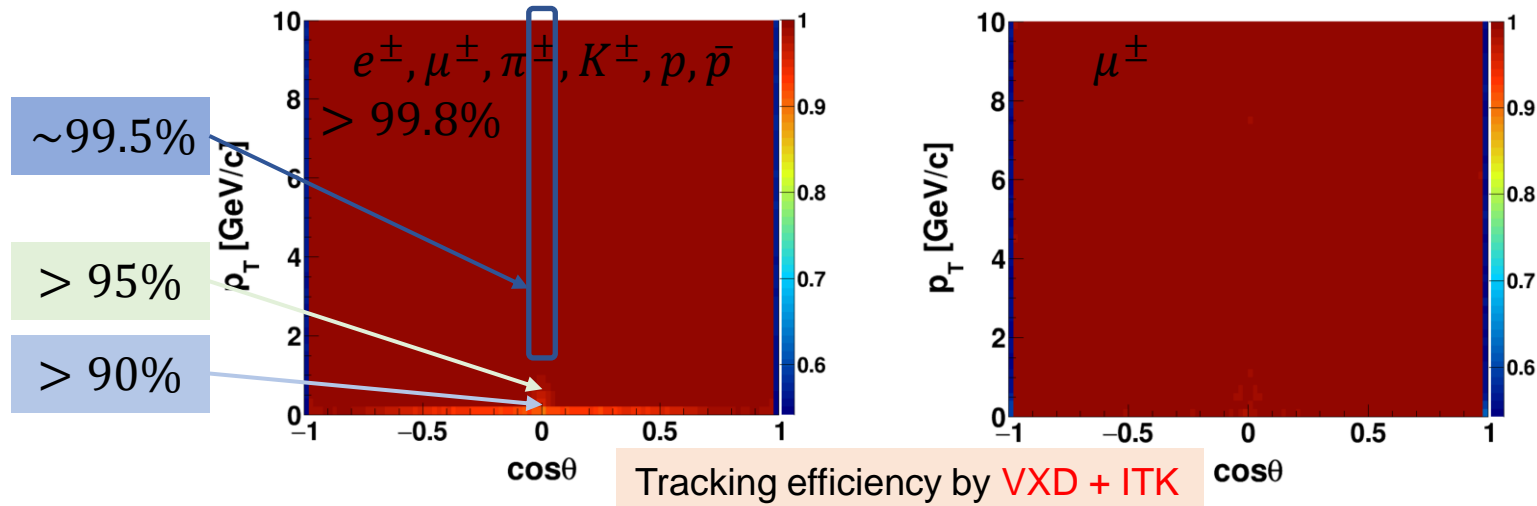
■ A complete reconstruction chain ready

- Support to reconstruct part of trackers through option sets

sets of tracking detectors	track objects
VXD only	VXDTracks
VXD + ITK	SiTracks
TPC only	ClupatraTracks (TPCTracks)
VXD + ITK + TPC	InnerTracks
VXD + ITK + OTK	FullSiTracks
ITK + TPC	CenterTracks
ITK + TPC + OTK	OuterTracks
VXD + ITK + TPC + OTK	CompleteTracks

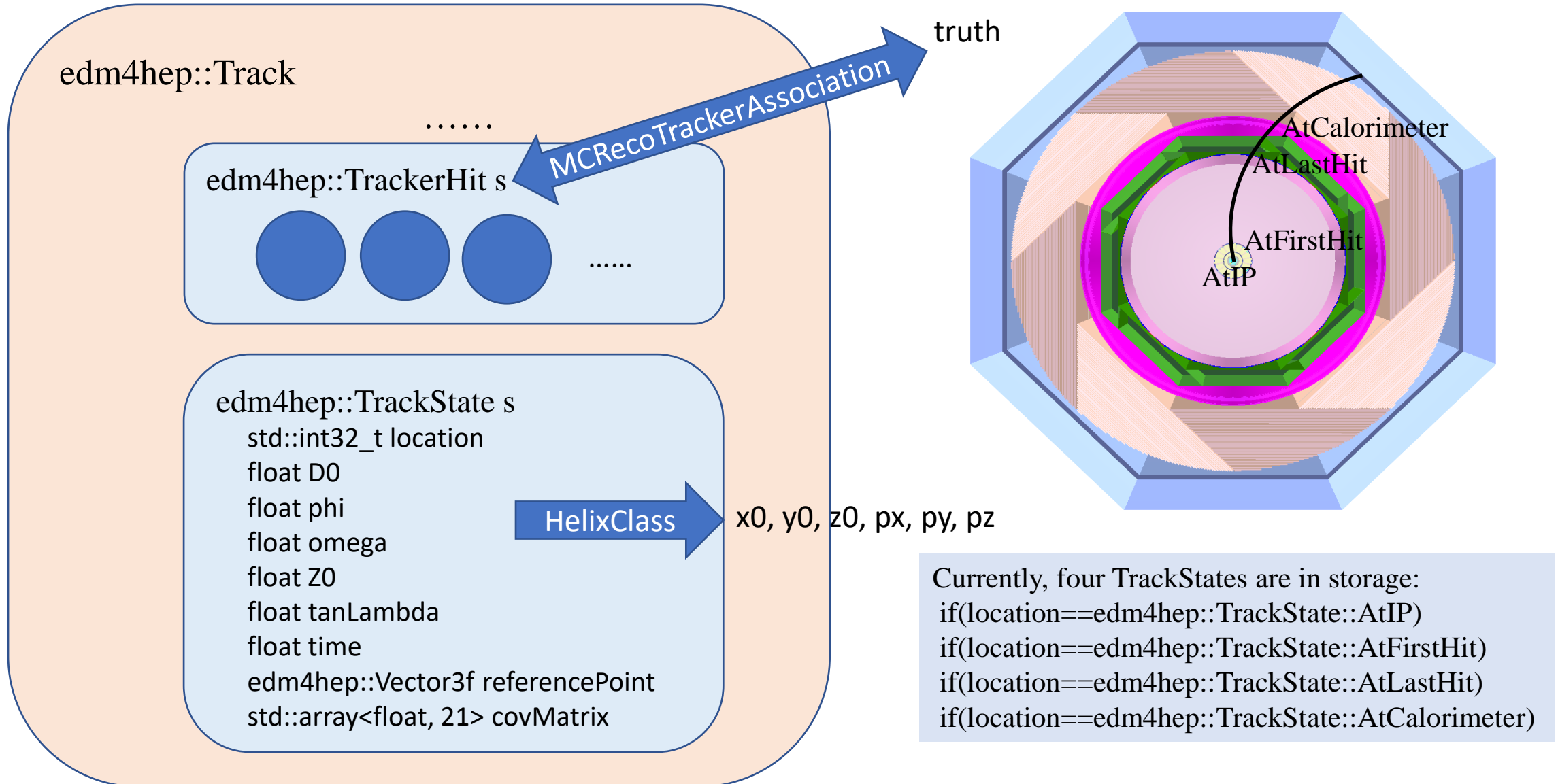
- More sets are optional such as ITK + OTK, helpful to study tracker performances for especial tracks (low momentum and decayed)

■ Performance estimation by full simulation



tdr25.1.2

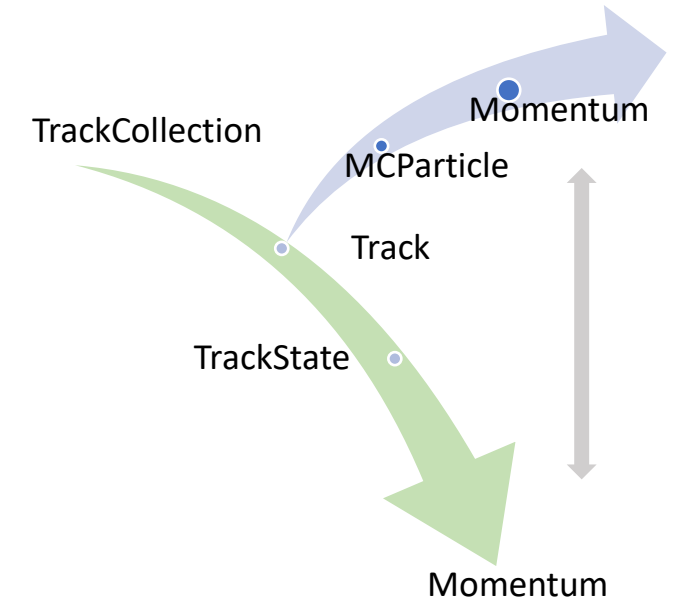
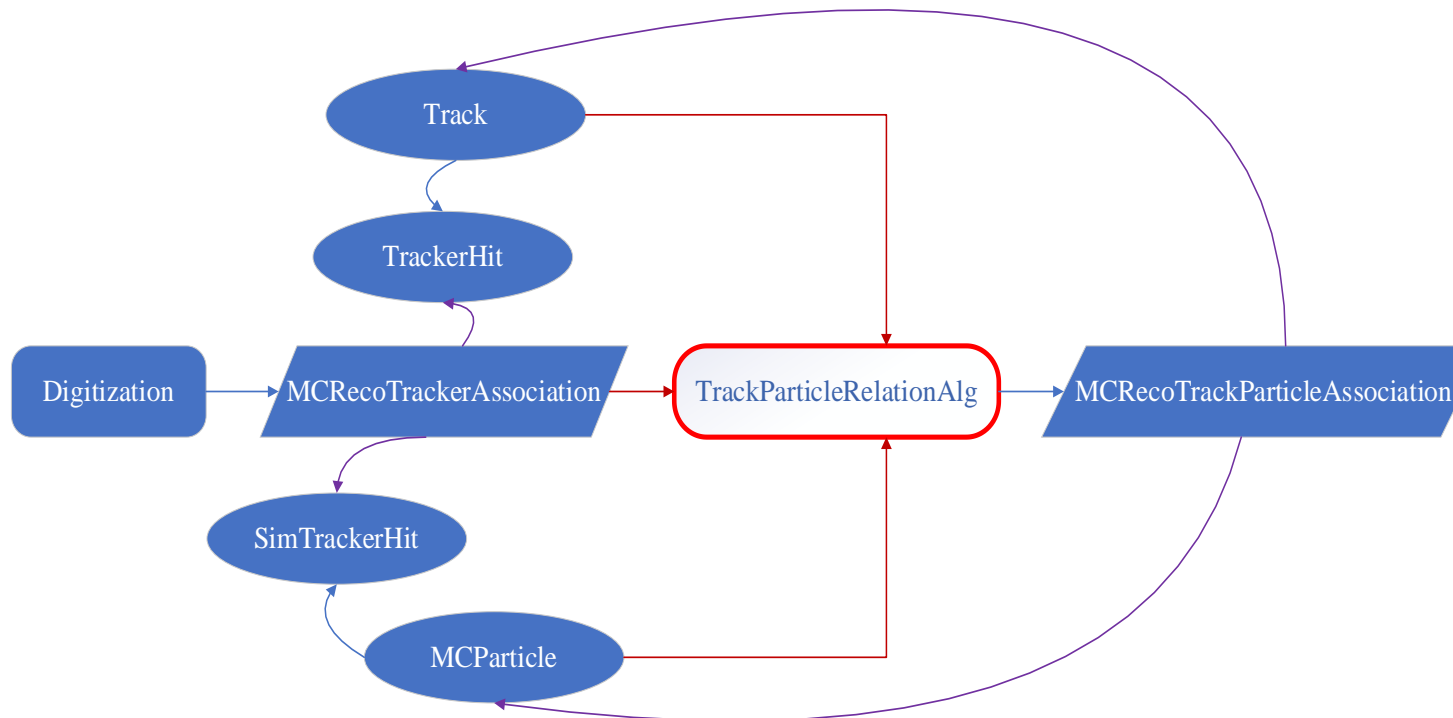
Output



Association

■ MCRcoTrackParticleAssociation

- Track
- MCParticle
- weight: number of tracker hit linked between MCParticle and Track (NL), for a particle, found track (minimum requirement: $NL_{maximum} \geq 4$)
- help to compare to MC truth



Geometry of ITKBarrel

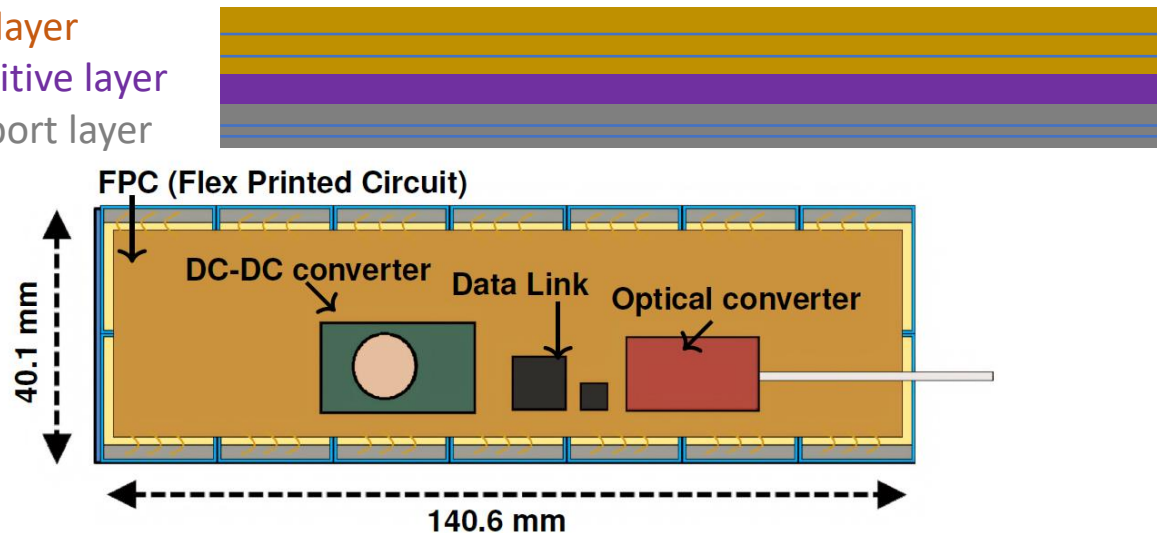
■ Previous version: SIT_StaggeredStave_v02.xml

- JIANG Xiaojie implemented
- non-uniform: DC-DC, optical, cooling

■ Updated version: ITK_StaggeredStave_v03_01.xml

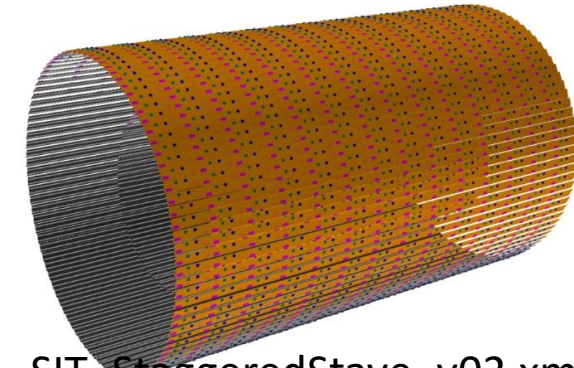
- uniform supper layer to fix issue at low momentum as preliminary
 - ✓ support: truss frame, carbon fleece, graphite foil, cooling pipe, cooling fluid, carbon fiber plate, glue
 - ✓ sensitive: by gaped modules (by gaped sensors with dead side)
 - ✓ flex: FPC, other electronics, glue
- ladder radius and number: 103→102

flex layer
sensitive layer
support layer



Information about staves, modules, and sensors used for 3 ITK barrels construction					
Barrel	Number of staves	Modules per stave	Sensors per module	Total number of sensors	Sensor area [m ²]
ITKB1	44	7	14	4312	1.72
ITKB2	64	10	14	8960	3.58
ITKB3	102	14	14	19992	8.00
Total	210			33264	13.31

Table 5.4: Information about staves, modules, and sensors used for 3 ITK barrels construction.



SIT_StaggeredStave_v02.xml

Barrel Stave:

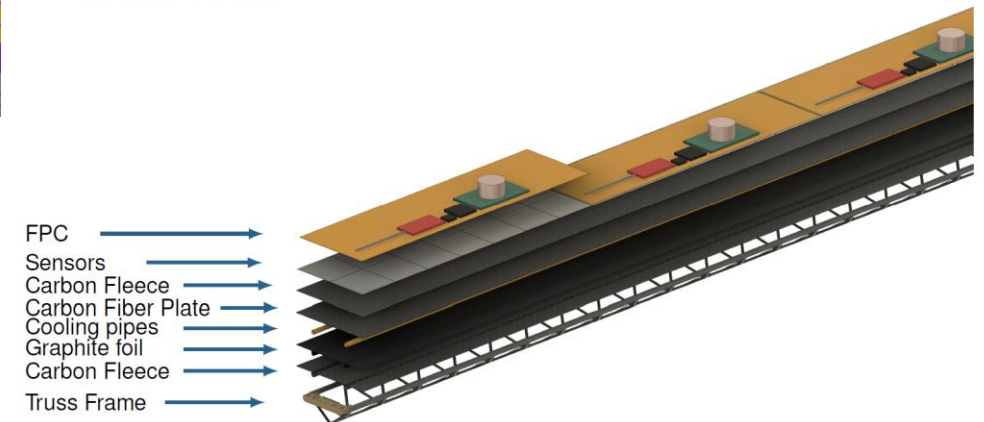


Figure 5.48: ITK barrel mechanics and cooling

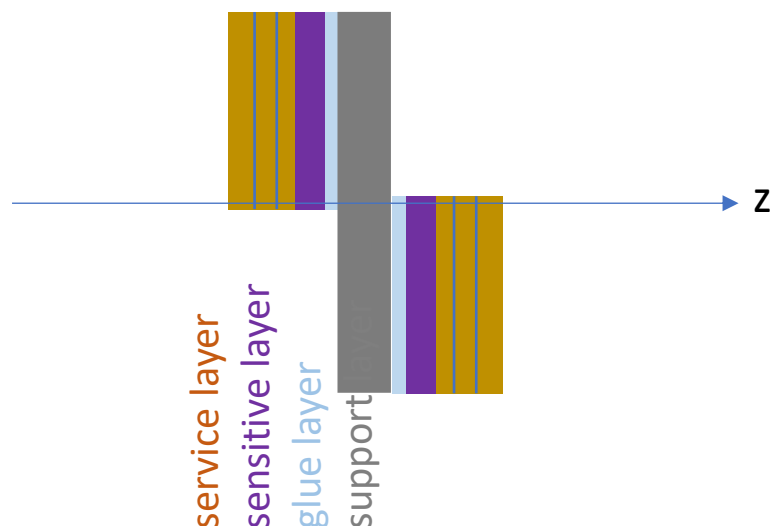
Geometry of ITKEndcap

■ Previous version: FTD_SkewRing_v01_07.xml

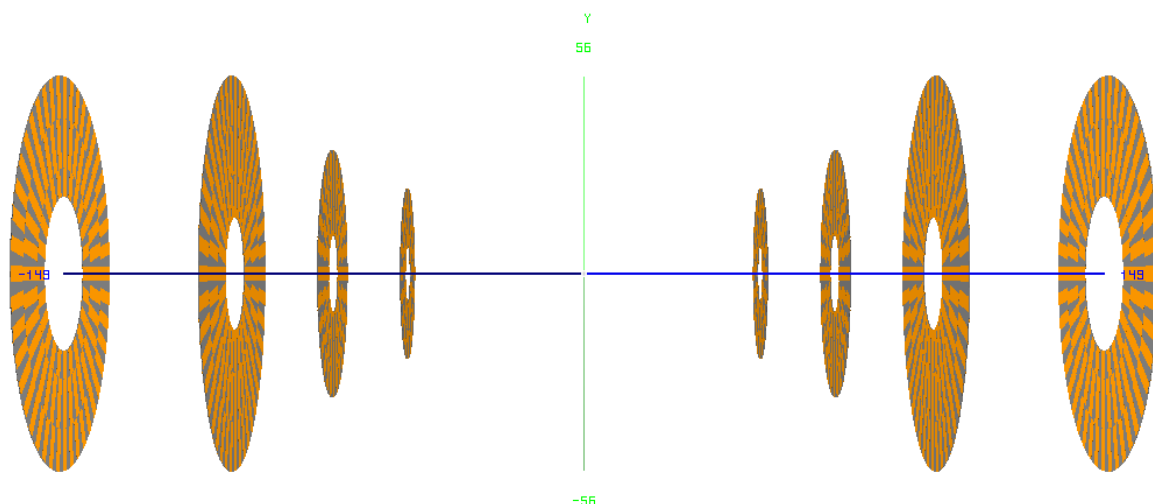
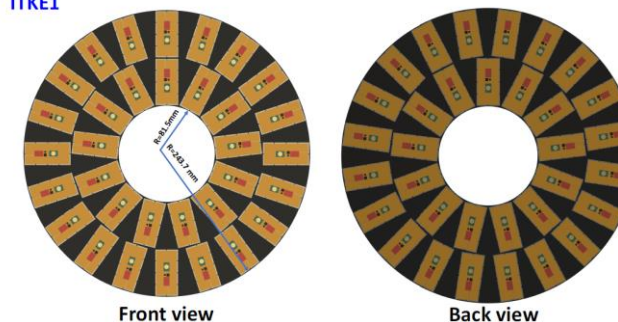
- 16 trapezoid petals with sensitive layer and support layer

■ Updated version: ITK_EndCap_v01.xml (MultiRingsZDisk)

- **support (disk)**: carbon fiber facesheet, cooling tube wall, cooling fluid, graphite foam+Honeycomb, carbon fiber plate facesheet
- **sensor: petal**
 - ✓ **glue**: glue
 - ✓ **sensitive**: silicon
 - ✓ **service**: glue, FPC, other electronics



a) ITKE1



The Module and Sensor Layout of a Single Face of Each ITK Endcap				
Endcap	Number of module rings	Number of modules per module ring	Number of sensors per module	Total sensors
ITKE1	2	13,20	8,8	264
ITKE2	3	16,24,28	8,8,8	544
ITKE3	3	24,36,44	12,14,14	1408
ITKE4	3	24,36,44	8,14,12	1224
Total				3440

Table 5.5: The Module and Sensor Layout of a Single Face of Each ITK Endcap

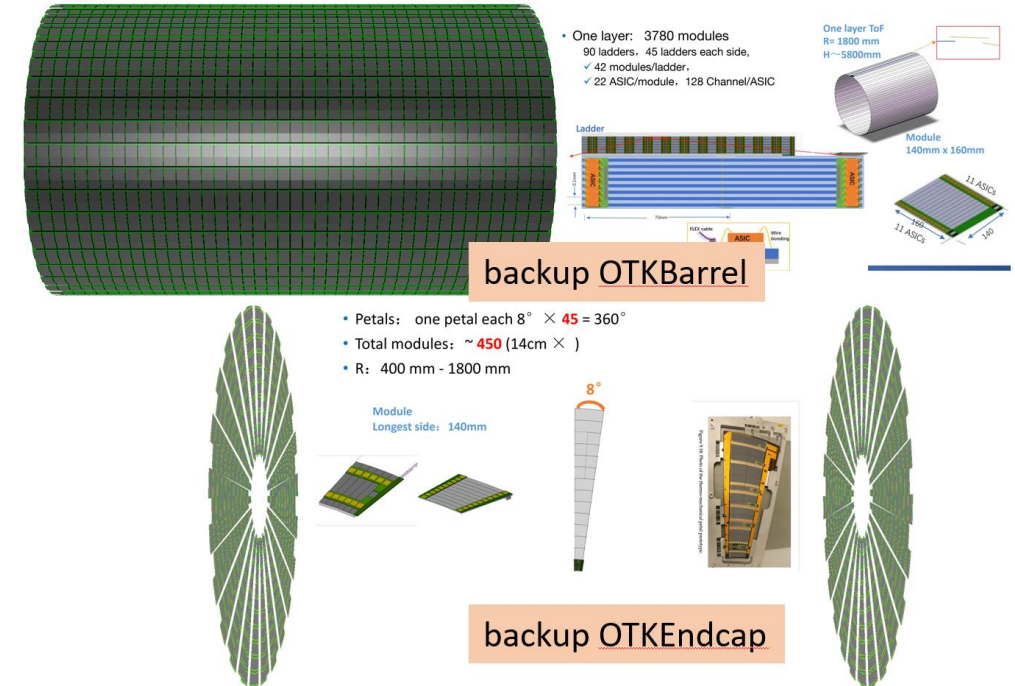
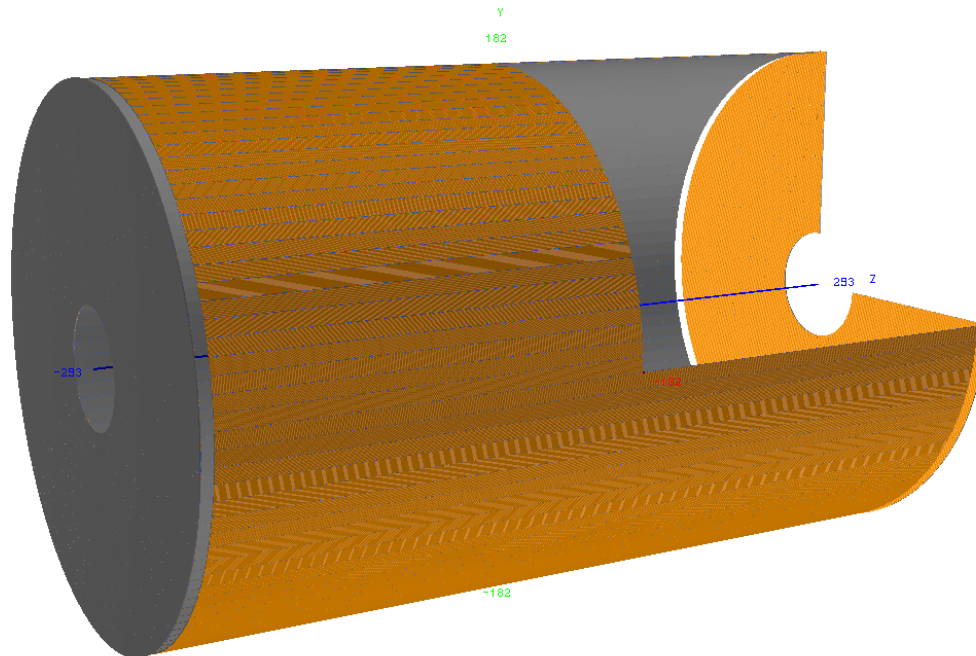
Geometry of OTK

■ Previous versions:

- OTKB: backup (YU Dian implemented)
- OTKE: 16 trapezoid petals, backup in patch

■ Updated versions: baseline (LI Zhihao implemented)

- OTKB: OTKBarrel_v02.xml
- OTKE: OTKEndcap_v02.xml



```
<ring name="A1" inner_radius=" 406*mm" outer_radius="( 534-0.2)*mm" repeat="16* 5" aggregation="2"
<ring name="A2" inner_radius=" 534*mm" outer_radius="( 662-0.5)*mm" repeat="16* 5" aggregation="2"
<ring name="B1" inner_radius=" 662*mm" outer_radius="( 790-0.2)*mm" repeat="16* 7" aggregation="2"
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<ring name="C2" inner_radius="1123*mm" outer_radius="(1255-0.2)*mm" repeat="16*10" aggregation="2"
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<ring name="C4" inner_radius="1324*mm" outer_radius="(1400-0.5)*mm" repeat="16*10" aggregation="1"
<ring name="D1" inner_radius="1400*mm" outer_radius="(1460-0.2)*mm" repeat="16*14" aggregation="1"
<ring name="D2" inner_radius="1460*mm" outer_radius="(1520-0.2)*mm" repeat="16*14" aggregation="1"
<ring name="D3" inner_radius="1520*mm" outer_radius="(1668-0.2)*mm" repeat="16*14" aggregation="2"
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```

Material

```
<flex length="ITKBarrel_ladder_length_1" width="ITKBarrel_module_width" material="Air" vis="SeeThrough">
  <slice name="Glue" thickness="100*um" material="CER_ITK" vis="YellowVis"/>
  <slice name="FPCInsulating" thickness="100*um" material="Polyimide_ITK" vis="YellowVis"/>
  <slice name="FPCMetal" thickness="100*um" material="G4_Al" vis="GrayVis"/>
  <slice name="OEComponent1" thickness=" 25*um" material="Kapton" vis="YellowVis"/>
  <slice name="OEComponent2" thickness=" 56*um" material="G4_POLYETHYLENE" vis="GreenVis"/>
  <slice name="OEComponent3" thickness=" 3*um" material="G4_Cu" vis="RedVis"/>
</flex>
```

Functional unit	Component	Material	Thickness [μm]	X ₀ [cm]	Radiation Length [% X ₀]
Sensor Module	FPC metal layers	Aluminium	100	8.896	0.112
	FPC Insulating layers	Polyimide	100	28.41	0.035
	Sensor	Silicon	150	9.369	0.160
	Glue		100	44.37	0.023
	Other electronics				0.050
Cooling Plate	Carbon fleece layers	Carbon fleece	40	106.80	0.004
	Carbon fiber plate	Carbon fiber	150	26.08	0.057
	Cooling tube wall	Polyimide	64	28.41	0.013
	Cooling fluid	Water		35.76	0.105
	Graphite foil	Graphite	30	26.56	0.011
	Glue	Cyanate ester resin	100	44.37	0.023
Truss Frame	Carbon rowing				0.080
Total					0.673

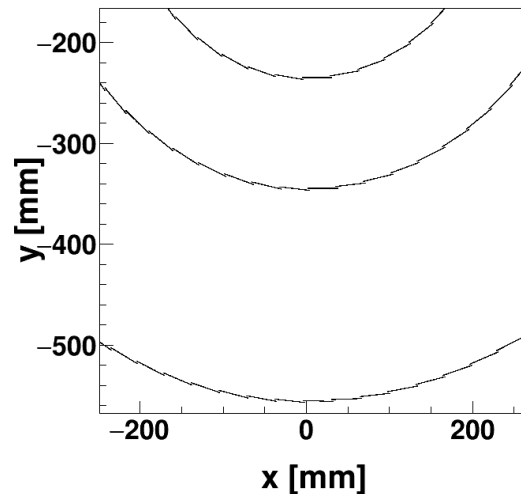
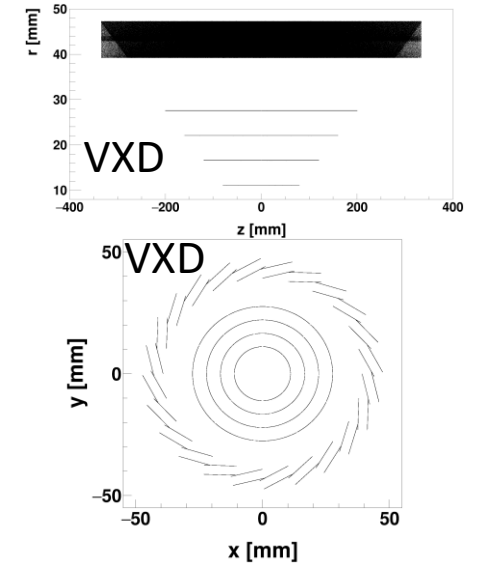
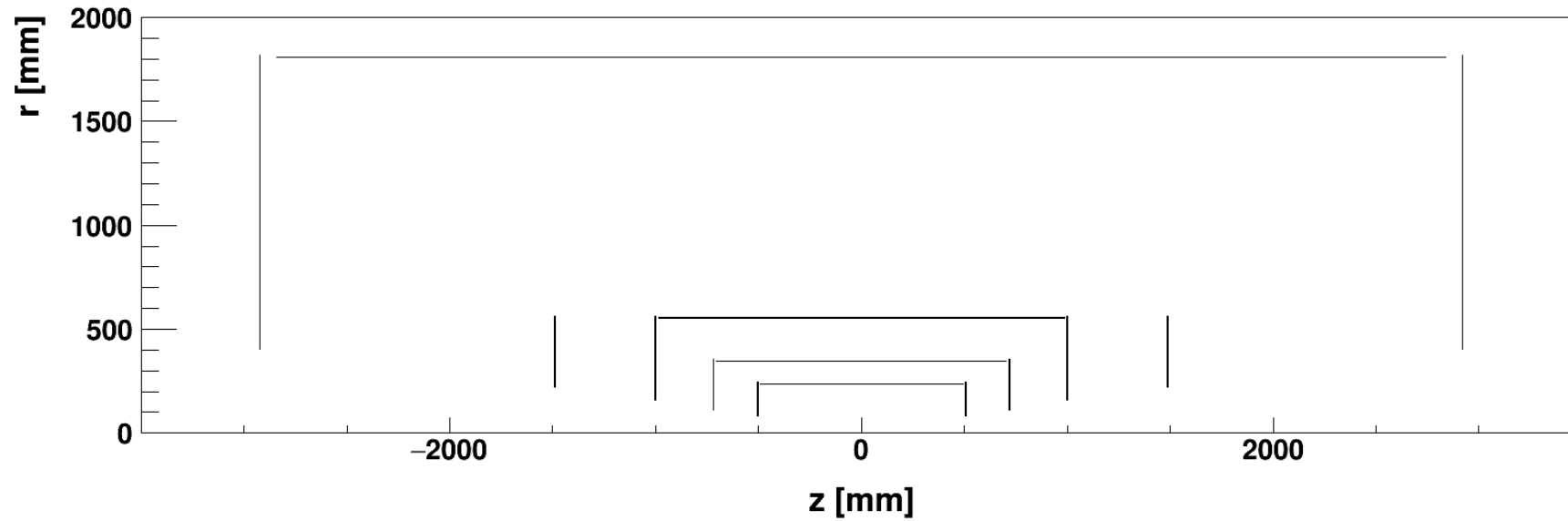
Table 5.9: Estimation of ITK stave material contributions

Num. \ Layer	Material \ Name	Atomic Number/Z	Mass/A [g/mole]	Density [g/cm3]	Radiation Length [cm]	Thickness [cm]	Integrated X ₀ [cm]
1	Air	7	14.801	0.0012	30392.1242	3.418	0.000112
2	CF_ITK	6	11.956	1.6088	26.0800	0.021	0.000910
3	CarbonFleece_ITK	6	12.011	0.3998	106.8000	0.002	0.000929
4	Graphite_ITK	6	12.011	1.6076	26.5600	0.003	0.001042
5	Polyimide_ITK	6	12.701	1.4282	28.4100	0.006	0.001267
6	G4_WATER	7	14.322	1.0000	36.0830	0.038	0.002317
7	CF_ITK	6	11.956	1.6088	26.0800	0.015	0.002892
8	CarbonFleece_ITK	6	12.011	0.3998	106.8000	0.002	0.002911
9	CER_ITK	7	13.326	0.8809	44.3700	0.010	0.003137
10	G4_Si	14	28.085	2.3300	9.3661	0.015	0.004738
11	CER_ITK	7	13.326	0.8809	44.3700	0.010	0.004963
12	Polyimide_ITK	6	12.701	1.4282	28.4100	0.010	0.005315
13	G4_Al	13	26.982	2.6990	8.8963	0.010	0.006440
14	Kapton	6	12.701	1.2430	32.6437	0.003	0.006516
15	G4_POLYETHYLENE	5	10.429	0.9400	47.6314	0.006	0.006634
16	G4_Cu	29	63.546	8.9600	1.4356	0.000	0.006843

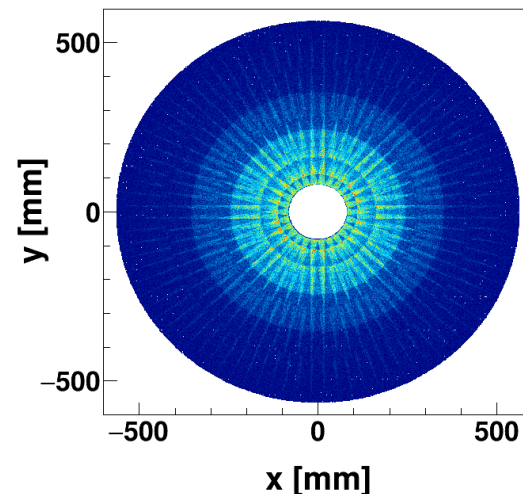
■ total 0.006843-0.000112=0.006731 of X₀

```
<support length="ITKBarrel_ladder_length_1" width="ITKBarrel_module_width" material="Air" vis="SeeThrough">
  <slice name="TrussFrame" thickness="208*um" width="ITKBarrel_module_width" material="CF_ITK" vis="LightGrayVis"/>
  <slice name="CarbonFleece" thickness=" 20*um" width="ITKBarrel_module_width" material="CarbonFleece_ITK" vis="LightGrayVis"/>
  <slice name="GraphiteFoil" thickness=" 30*um" width="ITKBarrel_module_width" material="Graphite_ITK" vis="GrayVis"/>
  <slice name="CoolingTube" thickness=" 64*um" width="ITKBarrel_module_width" material="Polyimide_ITK" vis="SeeThrough"/>
  <slice name="CoolingFluid" thickness="379*um" width="ITKBarrel_module_width" material="G4_WATER" vis="SeeThrough"/>
  <slice name="CFPlate" thickness="150*um" width="ITKBarrel_module_width" material="CF_ITK" vis="GrayVis"/>
  <slice name="CarbonFleece" thickness=" 20*um" width="ITKBarrel_module_width" material="CarbonFleece_ITK" vis="LightGrayVis"/>
  <slice name="Glue" thickness="100*um" width="ITKBarrel_module_width" material="CER_ITK" vis="GrayVis"/>
</support>
```

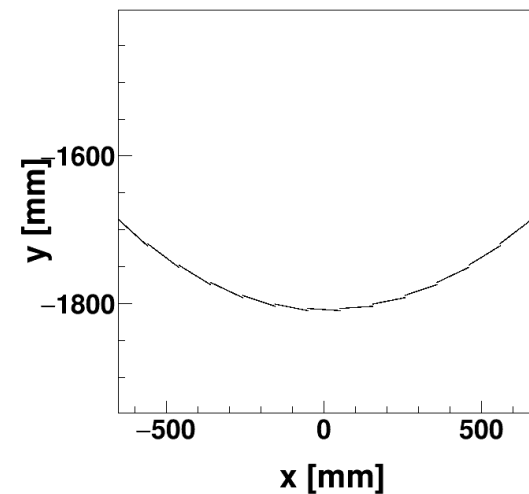
Positions of Hits of Silicon Trackers



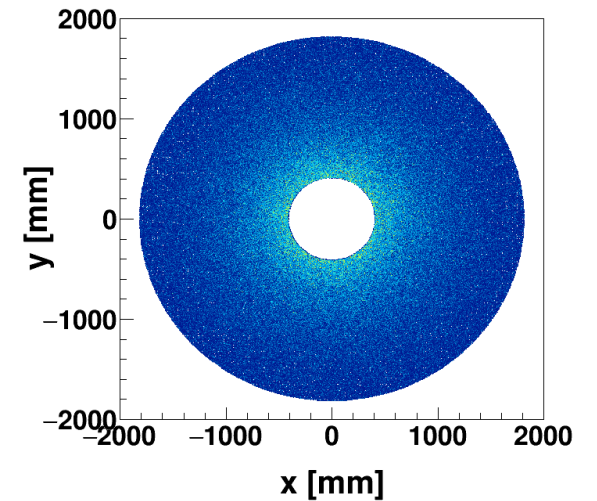
ITKBarrelCollection



ITKEndcapCollection



OTKBarrelCollection



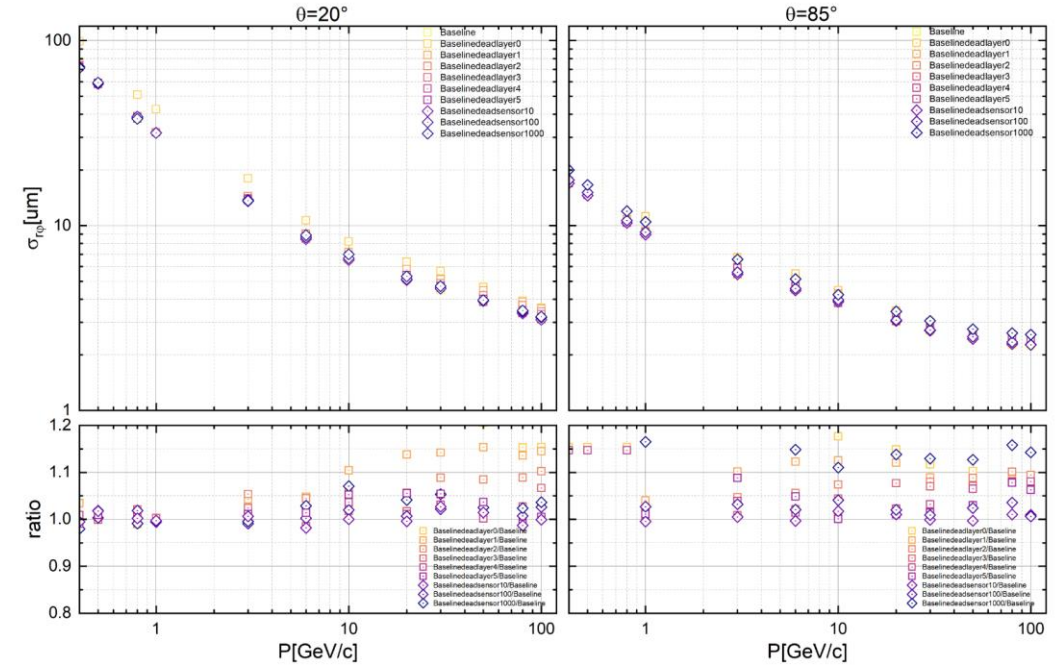
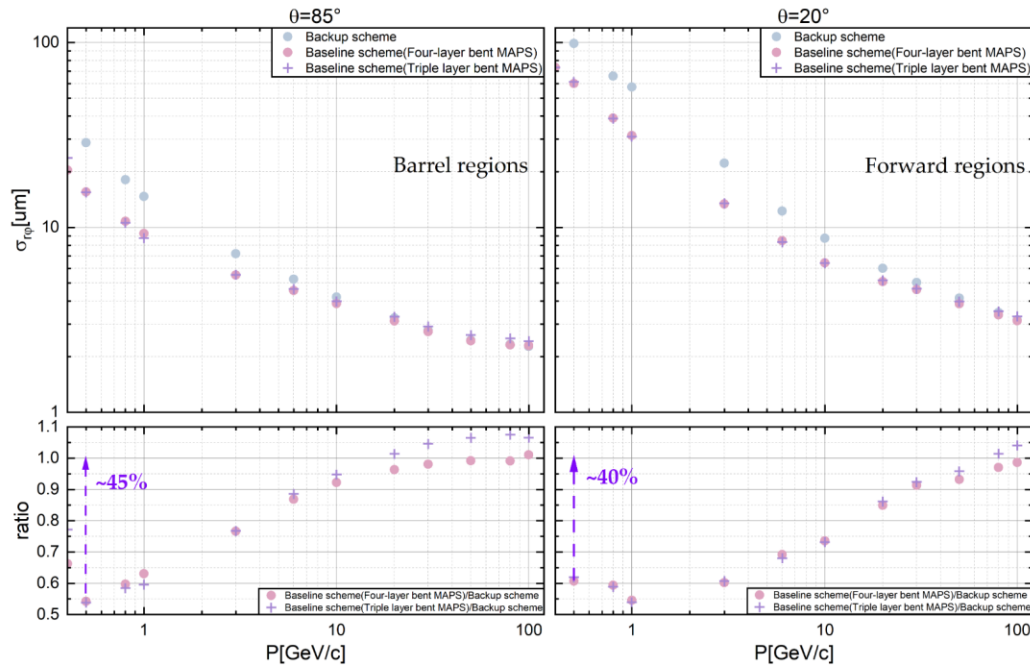
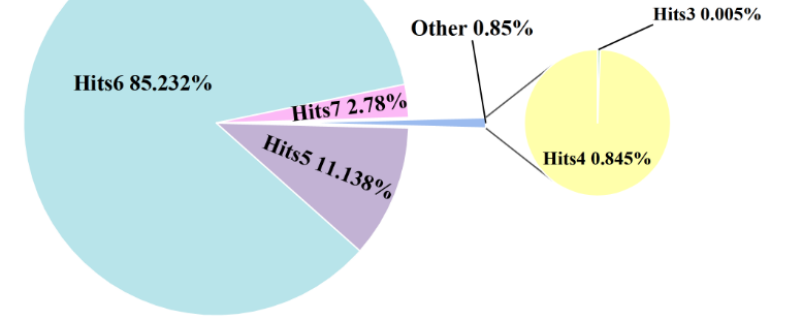
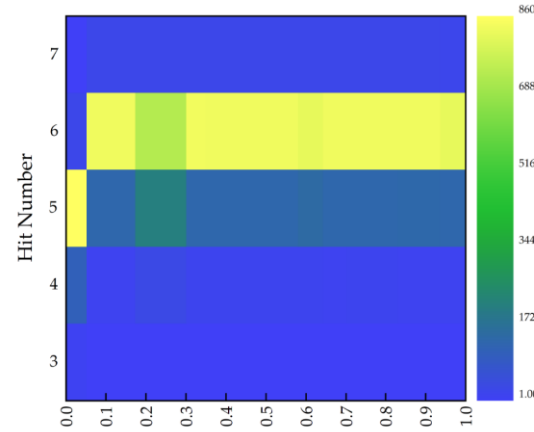
OTKEndcapCollection

Application on the Vertex Detector

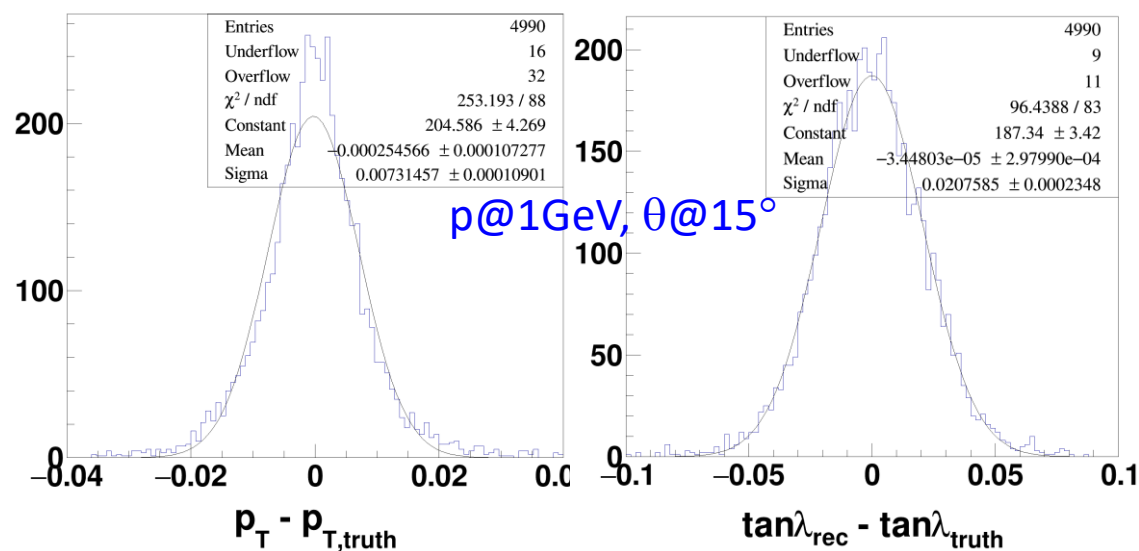
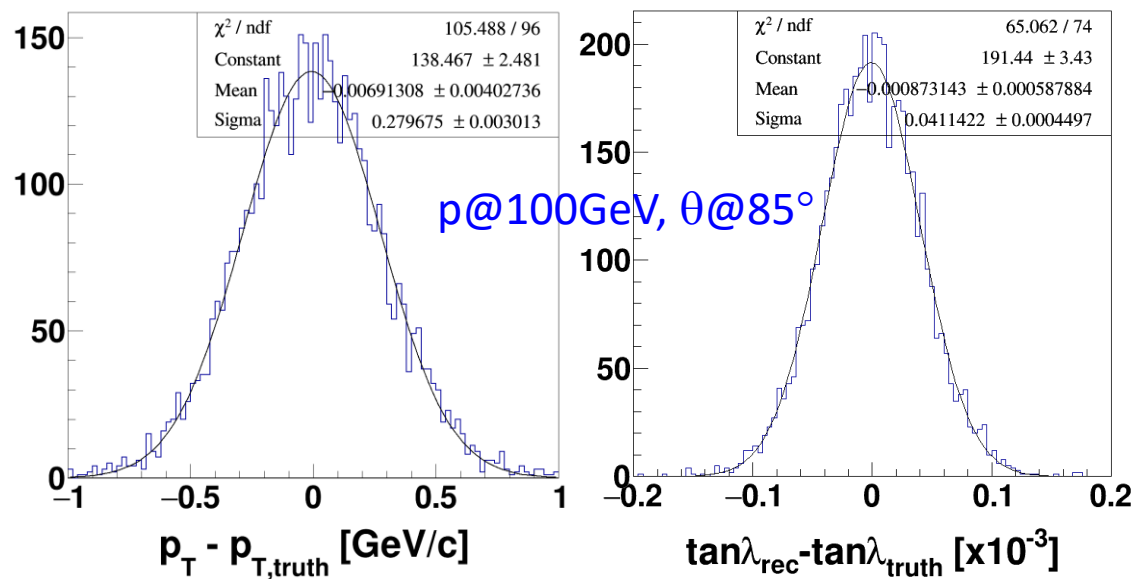
■ Perform performance comparison on different case in CEPCSW (ZHANG

Tianyuan)

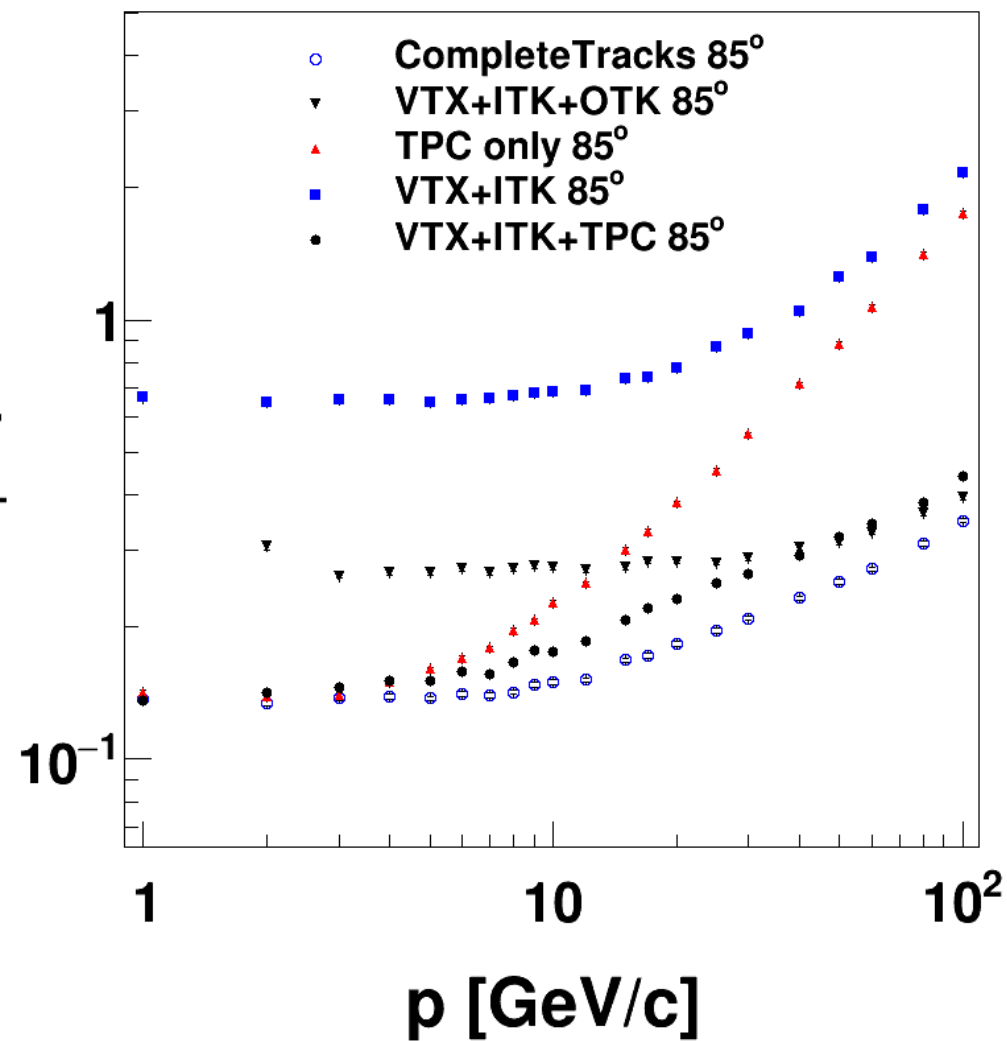
- Different schemes
- Hit number
- Dead sensors, even whole layer



Resolution



$\sigma_{p_T/p_T} (\%)$



Issues and Plan

■ Hit efficiency

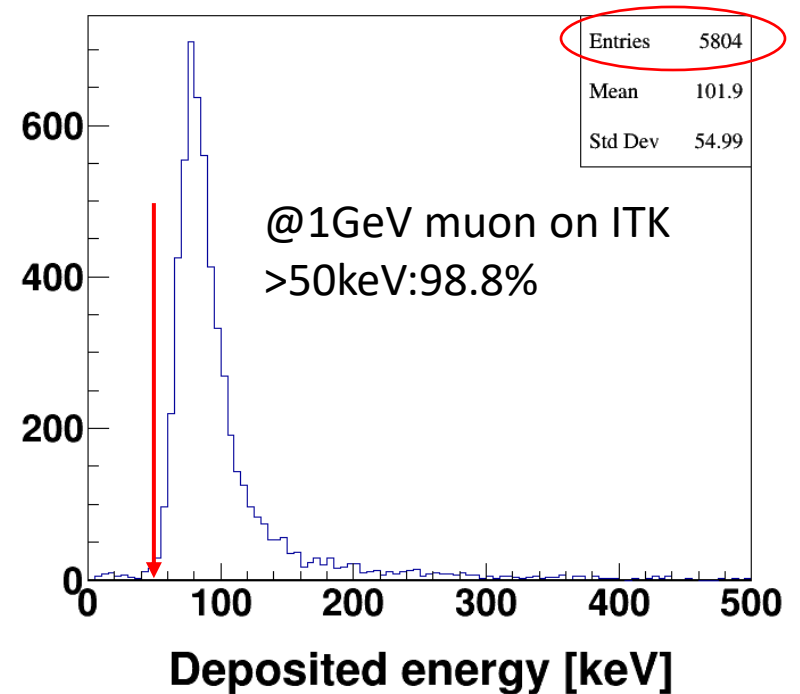
- Not perform threshold now
- To find out threshold about 99%?
- Effective thickness?

■ Software development

- Efficiency at low momentum and small polar angle
- Help tools
- Alignment

■ Performance estimation on special case

- Dead sensor
 - ✓ Hit drop according to deposited energy or efficiency
 - ✓ Hit drop in whole sensors
- Background mixing



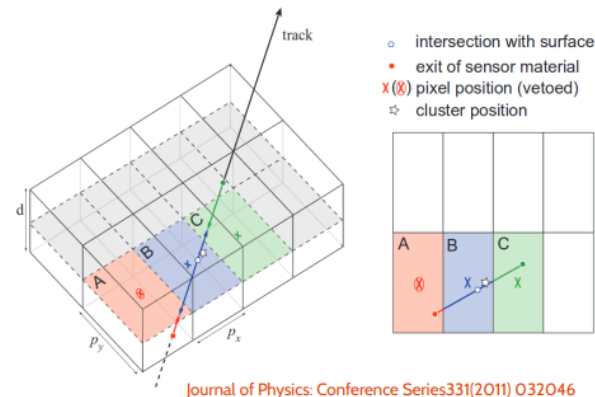
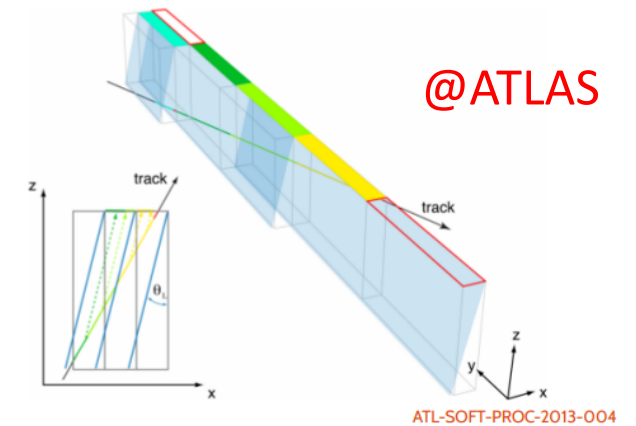
Fast Digitization

- To create a fast digitization similar with ATLAS
 - Without charge amplitude
 - ongoing: by LU Hancen
- For vertex detector
 - Charge deposited
- For CMOS pixel/strip
 - Charge deposited
- For AC-LGAD
 - Charge deposited
- Estimate hit rate on merged hits while simulation
- Effective thickness?
 - Charge collected

Fast Digitization: Silicon Tracker

Simplified digitization of the signal based on simply geometry projection.

- Local entry and exit point in the detector module from the detector simulation.
- Evaluate the step in each sensor.
- Charge deposited in each pixel proportional to the step.
- Project the charge on the surface taking into account the Lorentz shift (θ_L).



- Create the clusters directly in digitization step merging all the pixels crossed by a single track
- Set a threshold to path length
- Propagate the truth informations to the reconstruction.

Summary

- Full simulation chain for tracker has been created in CEPCSW
 - Output edm4hep SimTrackerHit, TrackerHit, Track and association
 - Helix tool to obtain momentum
 - Apply on performance study and PFA, muon ID ongoing
- Baseline silicon trackers has been implemented: ITKB, ITKE, OTKB, OTKE
 - TDR baseline detector geometry TDR_o1_v01 close to forezen
- Towards TDR
 - Tracking under dead sensors
 - Tracking under background
- Future
 - Fast digitization
 - Alignment